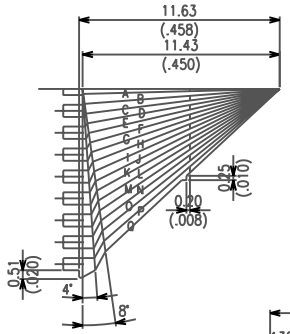
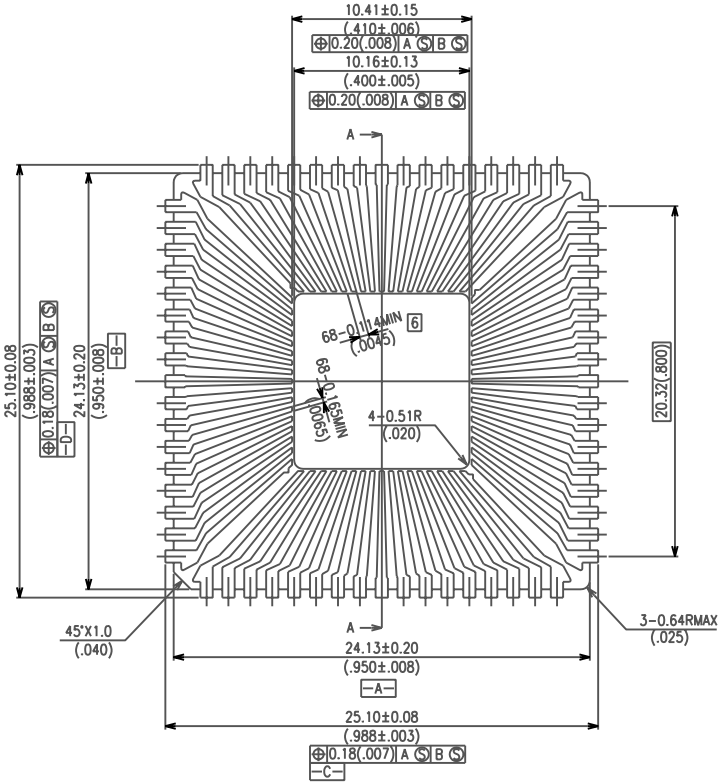
SSM P/N CQJ06817

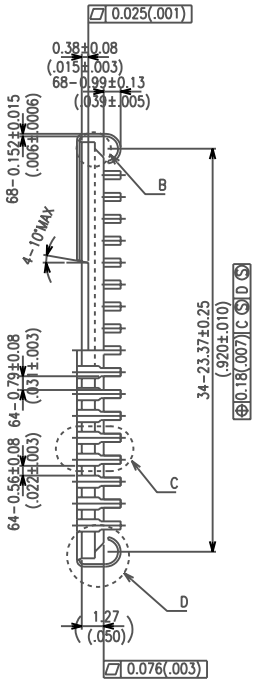
NOTES
1.MATERIALS:
CERAMIC TO OPAQUE,90-94% AL_2O_3
SOLDER GLASS TO BE 7583.
MAX PULLBACK TO BE 0.25(.010)
FROM CERAMIC EDGE.
DIE ATTACH AREA TO BE Au. 120
MICROINCH MIN.
LEAD FRAME TO BE ALLOY 42
TYPE B MIL 38510 PARAGRAGH 3.5.6.1
WITH ALUMINIUM BOND PADS. 100MICROINCH THICK
AND 35 MILS IN LENGTH WITH NO
PULL BACK.
3.THERE WILL BE NO UNSUPPORTED
BOND PADS GRETER THAN 0.25(.010)
4.ADJACENT BOND PADS MUST BE
CO-PLANAR WITHIN 0.15(.006).
TOTAL CO-PLANARITY NO GREATER
THAN 0.25(.010)
5 THERE WILL BE NO NICKS. CUTS
OR GLASS IN THE BOND RADIUS
6 MINIMUM INTERNAL METAL SEPARATION, OTHER THAN BOND
FINGERS, TO BE 0.13(.005)

A	1.45°
B	4.37°
C	7.27°
D	10.13°
E	12.98°
F	15.80°
G	18.57°
H	21.28°
I	23.97°
J	26.57°
K	29.12°
L	31.60°
M	34.03°
N	36.38°
O	38.65°
P	40.87°
Q	43.00°

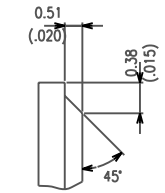


LEADTIP DETAIL

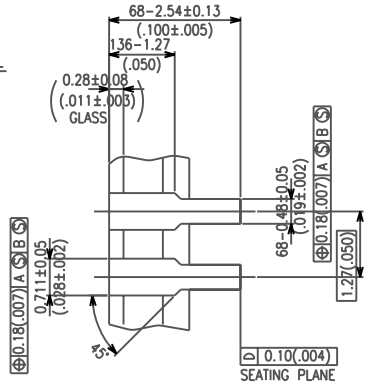




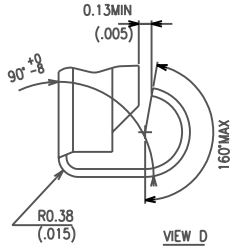
SECTION A-A



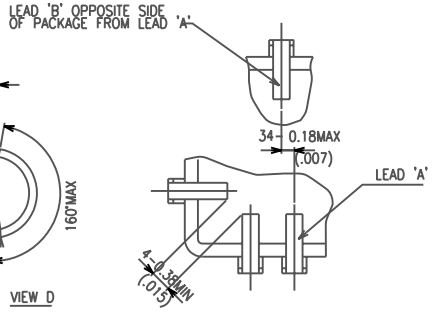
VIEW B



VIEW C



VIEW D



JEDEC TYPE

MODIFICATIONS	CHANGE	DATE	DRAWN	CHECKED	APPROVED

NAME: 68LD QUAD CERPAC 'J'(950-400)
SCALE: 5 : 1
MATERIAL: ——
TOLERANCES: UNLESS OTHERWISE SPECIFIED
DRAWN: K.OKADA
CHECKED:
APPROVED:
DATE: JUN.15'88
KYOCERA CORPORATION, KYOTO JAPAN
DWG No. QC-068271-J-1

SPECTRUM SEMICONDUCTOR MATERIALS, INC.
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